

21. (New) The method of claim 19, further comprising the step of adding at least one gas selected from the group of  $O_2$ ,  $N_2O$ ,  $NO$ ,  $NO_x$ ,  $CO_2$ ,  $Ar$ ,  $NO_2$  and  $N_2$  to the process gas at least from time to time.

22. (New) The method of claim 19, further comprising the step of adding at least one of an additive, a fluoroalkane and  $NF_3$  for consuming the at least one passivating material to the process gas at least from time to time, the at least one passivating material including one of  $SiO_2$  and a teflon-type material, and the at least one additive including at least one of  $CHF_3$ ,  $CF_4$ ,  $C_2F_6$ ,  $C_3F_6$ ,  $C_4F_8$ ,  $C_4F_{10}$  and  $C_3F_8$ .

23. (New) The method of claim 19, further comprising the step of adding at least one of a light and easily ionizable gas,  $H_2$ ,  $He$  and  $Ne$  to the process gas at least from time to time.

24. (New) A method of anisotropic plasma etching a laterally defined structure in a silicon substrate using a process gas, the method comprising the steps of:

precipitating at least one passivating material at least on a side wall of the laterally defined structure at least from time to time at least one of prior to the anisotropic plasma etching and during the anisotropic plasma etching; and

adding  $NF_3$  to the process gas at least from time to time as an additive for consuming at least one of the at least one passivating material,  $SiO_2$  and a teflon-type material.

25. (New) The method of claim 24, further comprising the step of adding a fluorine-delivering etching gas to the process gas at least from time to time, the fluorine-delivering etching gas including at least one compound selected from the group of  $SF_6$ ,  $ClF_3$ ,  $BrF_3$  and  $IF_5$ .

26. (New) The method of claim 24, further comprising the step of adding at least one gas selected from the group of  $SiF_4$ ,  $C_4F_8$ ,  $C_3F_6$ ,  $C_4F_{10}$ ,  $C_3F_8$  and  $C_2F_6$  to the process gas at least from time to time as a gas forming the at least one passivating material.

27. (New) The method of claim 24, further comprising the step of adding at least one gas selected from the group of  $O_2$ ,  $N_2O$ ,  $NO$ ,  $NO_x$ ,  $CO_2$ ,  $Ar$ ,  $NO_2$  and  $N_2$  to the process gas at least from time to time.

28. (New) The method of claim 24, further comprising the step of adding at least one of a light and easily ionizable gas,  $H_2$ , He and Ne to the process gas at least from time to time.

29. (New) A method of anisotropic plasma etching a laterally defined structure in a silicon substrate using a process gas, the method comprising the steps of:

precipitating a passivating material on at least one side wall of the laterally defined structure at least from time to time at least one of prior to the anisotropic plasma etching and during the anisotropic plasma etching; and

adding at least one of a light and easily ionizable gas,  $H_2$ , He and Ne to the process gas at least from time to time.

30. (New) The method of claim 29, further comprising the step of adding at least one fluorine-delivering etching gas to the process gas at least from time to time, the fluorine-delivering etching gas including at least one of a compound selected from the group of  $SF_6$ ,  $ClF_3$ ,  $BrF_3$  and  $IF_5$ .

31. (New) The method of claim 29, further comprising the step of adding at least one gas selected from the group  $SiF_4$ ,  $C_4F_8$ ,  $C_3F_6$ ,  $C_4F_{10}$ ,  $C_3F_8$  and  $C_2F_6$  to the process gas at least from time to time as a gas forming the at least one passivating material.

32. (New) The method of claim 29, further comprising the step of adding at least one gas selected from the group of  $O_2$ ,  $N_2O$ , NO,  $NO_x$ ,  $CO_2$ , Ar,  $NO_2$  and  $N_2$  to the process gas at least from time to time.

33. (New) The method of claim 29, further comprising the step of adding at least one of an additive, a fluoroalkane and  $NF_3$  to the process gas at least from time to time for consuming at least one of the at least one passivating material,  $SiO_2$  and a teflon-type material, the additive including one of  $CHF_3$ ,  $CF_4$ ,  $C_2F_6$ ,  $C_3F_6$ ,  $C_4F_8$ ,  $C_4F_{10}$  and  $C_3F_8$ .

34. (New) A method of anisotropic plasma etching a laterally defined structure in a silicon substrate using a process gas, the method comprising the steps of: